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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	384
Number of Logic Elements/Cells	1728
Total RAM Bits	32768
Number of I/O	146
Number of Gates	50000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2s50e-6pq208i



Spartan-IIE FPGA Family: Functional Description

DS077-2 (v3.0) August 9, 2013

Product Specification

Architectural Description

Spartan-IIE FPGA Array

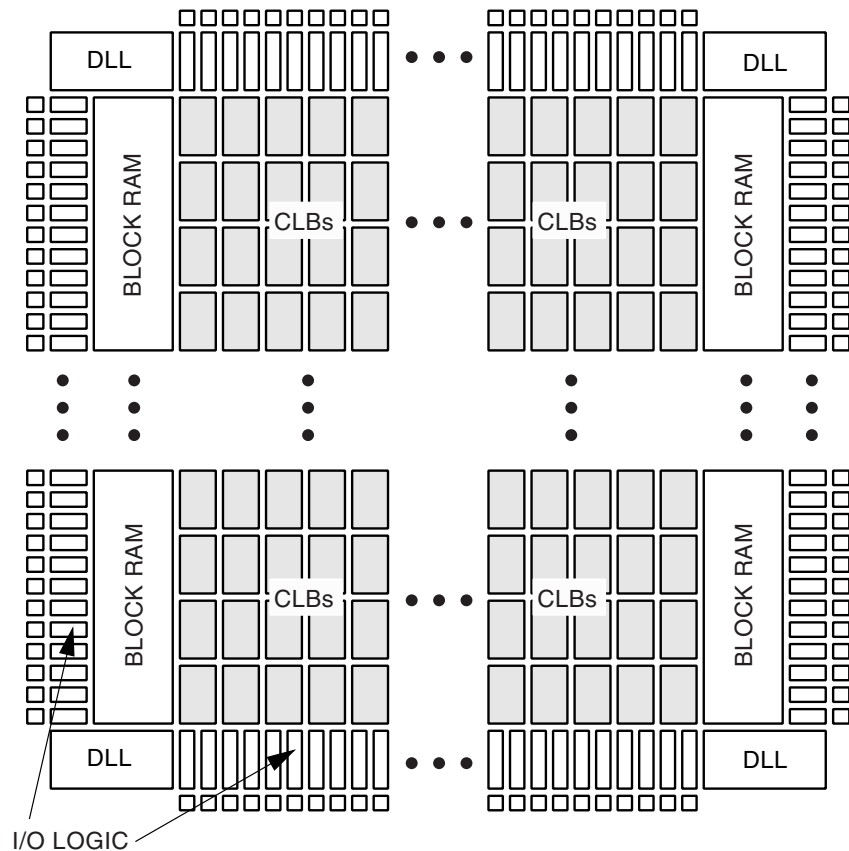
The Spartan®-IIE user-programmable gate array, shown in [Figure 3](#), is composed of five major configurable elements:

- IOBs provide the interface between the package pins and the internal logic
- CLBs provide the functional elements for constructing most logic
- Dedicated block RAM memories of 4096 bits each
- Clock DLLs for clock-distribution delay compensation and clock domain control
- Versatile multi-level interconnect structure

As can be seen in [Figure 3](#), the CLBs form the central logic structure with easy access to all support and routing structures. The IOBs are located around all the logic and memory elements for easy and quick routing of signals on and off the chip.

Values stored in static memory cells control all the configurable logic elements and interconnect resources. These values load into the memory cells on power-up, and can reload if necessary to change the function of the device.

Each of these elements will be discussed in detail in the following sections.



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Figure 3: Basic Spartan-IIE Family FPGA Block Diagram

Configurable Logic Block

The basic building block of the Spartan-IIE FPGA CLB is the logic cell (LC). An LC includes a 4-input function generator, carry logic, and storage element. The output from the function generator in each LC drives the CLB output or the D input of the flip-flop. Each Spartan-IIE FPGA CLB contains four LCs, organized in two similar slices; a single slice is shown in [Figure 6](#).

In addition to the four basic LCs, the Spartan-IIE FPGA CLB contains logic that combines function generators to provide functions of five or six inputs.

Look-Up Tables

Spartan-IIE FPGA function generators are implemented as 4-input look-up tables (LUTs). In addition to operating as a function generator, each LUT can provide a 16 x 1-bit synchronous RAM. Furthermore, the two LUTs within a slice can be combined to create a 16 x 2-bit or 32 x 1-bit synchronous RAM, or a 16 x 1-bit dual-port synchronous RAM.

The Spartan-IIE FPGA LUT can also provide a 16-bit shift register that is ideal for capturing high-speed or burst-mode data. This mode can also be used to store data in applications such as Digital Signal Processing.

Storage Elements

Storage elements in the Spartan-IIE FPGA slice can be configured either as edge-triggered D-type flip-flops or as level-sensitive latches. The D inputs can be driven either by function generators within the slice or directly from slice inputs, bypassing the function generators.

In addition to Clock and Clock Enable signals, each slice has synchronous set and reset signals (SR and BY). SR forces a storage element into the initialization state specified for it in the configuration. BY forces it into the opposite state. Alternatively, these signals may be configured to operate asynchronously.

All control signals are independently invertible, and are shared by the two flip-flops within the slice.

During start-up, the device performs four operations:

1. The assertion of DONE. The failure of DONE to go High may indicate the unsuccessful loading of configuration data.
2. The release of the Global Three State (GTS). This activates all the I/Os to which signals are assigned. The remaining I/Os stay in a high-impedance state with internal weak pull-up resistors present.
3. The release of the Global Set Reset (GSR). This allows all flip-flops to change state.
4. The assertion of Global Write Enable (GWE). This allows all RAMs and flip-flops to change state.

By default, these operations are synchronized to CCLK. The entire start-up sequence lasts eight cycles, called C0-C7, after which the loaded design is fully functional. The four operations can be selected to switch on any CCLK cycle C1-C6 through settings in the Xilinx Development Software. The default timing for start-up is shown in the top half of Figure 17; heavy lines show default settings.

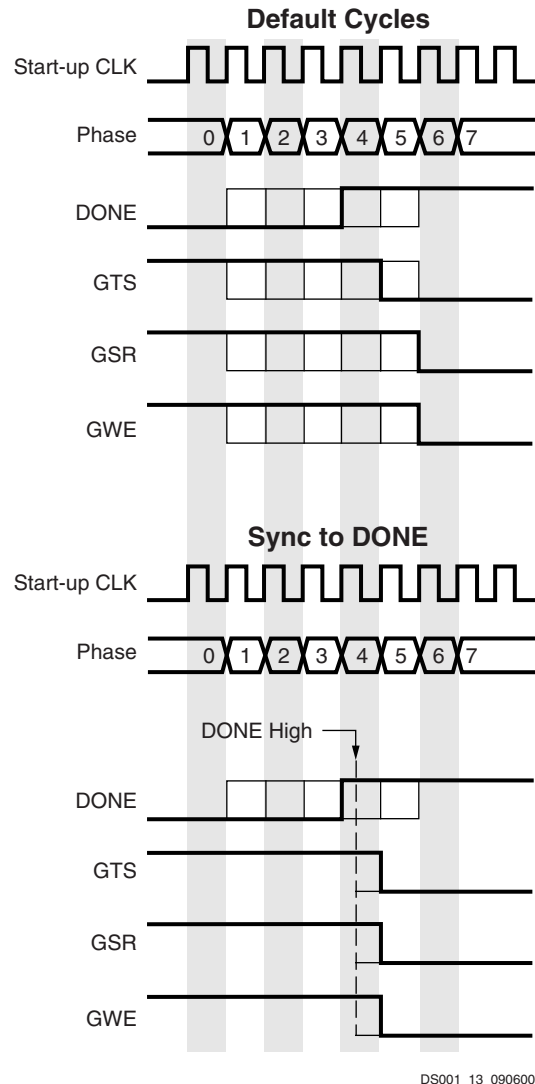
The default Start-up sequence is that one CCLK cycle after DONE goes High, the global 3-state signal (GTS) is released. This permits device outputs to turn on as necessary.

One CCLK cycle later, the Global Set/Reset (GSR) and Global Write Enable (GWE) signals are released. This permits the internal storage elements to begin changing state in response to the logic and the user clock.

The bottom half of Figure 17 shows another commonly used version of the start-up timing known as Sync-to-DONE. This version makes the GTS, GSR, and GWE events conditional upon the DONE pin going High. This timing is important for a daisy chain of multiple FPGAs in serial mode, since it ensures that all FPGAs go through start-up together, after all their DONE pins have gone High.

Sync-to-DONE timing is selected by setting the GTS, GSR, and GWE cycles to a value of DONE in the configuration options. This causes these signals to transition one clock cycle after DONE externally transitions High.

The sequence can also be paused at any stage until lock has been achieved on any or all DLLs.



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Figure 17: Start-Up Waveforms

Serial Modes

There are two serial configuration modes. In Master Serial mode, the FPGA controls the configuration process by driving CCLK as an output. In Slave Serial mode, the FPGA passively receives CCLK as an input from an external agent (e.g., a microprocessor, CPLD, or second FPGA in master mode) that is controlling the configuration process. In both modes, the FPGA is configured by loading one bit per CCLK cycle. The MSB of each configuration data byte is always written to the DIN pin first.

See Figure 18 for the sequence for loading data into the Spartan-IIE FPGA serially. This is an expansion of the "Load Configuration Data Frames" block in Figure 16, page 23. Note that $\overline{CS}$ and $\overline{WRITE}$ are not normally used during serial configuration. To ensure successful loading of the FPGA, do not toggle $\overline{WRITE}$ with $\overline{CS}$ Low during serial configuration.

Power-On Requirements

Spartan®-IIE FPGAs require that a minimum supply current I_{CCPO} be provided to the V_{CCINT} lines for a successful power-on. If more current is available, the FPGA can consume more than I_{CCPO} min., though this cannot adversely affect reliability.

A maximum limit for I_{CCPO} is not specified. Be careful when using foldback/crowbar supplies and fuses. It is possible to control the magnitude of I_{CCPO} by limiting the supply current available to the FPGA. A current limit below the trip level will avoid inadvertently activating over-current protection circuits.

Symbol	Description				Min ⁽¹⁾	Typ	Max	Units
I _{CCPO}	Total V _{CCINT} supply current required during power-on	Commercial	XC2S50E - XC2S300E	After PCN ⁽²⁾	300	-	-	mA
				Before PCN ⁽²⁾	500	-	-	mA
			XC2S400E - XC2S600E			500	-	-
		Industrial	XC2S50E - XC2S300E	After PCN ⁽²⁾	500	-	-	mA
				Before PCN ⁽²⁾	2	-	-	A
			XC2S400E - XC2S600E			700	-	-
T _{CCPO}	V _{CCINT} ^(3,4) ramp time		After PCN ⁽²⁾		500	-	-	μs
			Before PCN ⁽²⁾		2	-	50	ms
I _{HSPO}	AC current per pin during power-on in hot-swap applications when V _{IN} > V _{CCO} + 0.4V; duration < 10ns		After PCN ⁽²⁾		-	±60	-	μA

Notes:

1. The I_{CCPO} requirement applies for a brief time (commonly only a few milliseconds) when V_{CCINT} ramps from 0 to 1.8V.
2. Devices built after the Product Change Notice PCN 2002-05 (see http://www.xilinx.com/support/documentation/customer_notices/pcn2002-05.pdf) have improved power-on requirements. Devices after the PCN have a 'T' preceding the date code as referenced in the PCN. Note that the XC2S150E, XC2S400E, and XC2S600E always have this mark. Devices before the PCN have an 'S' preceding the date code. Note that devices before the PCN are measured with V_{CCINT} and V_{CCO} powering up simultaneously.
3. The ramp time is measured from GND to 1.8V on a fully loaded board.
4. V_{CCINT} must not dip in the negative direction during power on.
5. I/Os are not guaranteed to be disabled until V_{CCINT} is applied.
6. For more information on designing to meet the power-on specifications, refer to the application note [XAPP450 "Power-On Current Requirements for the Spartan-II and Spartan-IIE Families"](#).

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for V_{OL} and V_{OH} are guaranteed output voltages over the recommended operating conditions. Only selected standards are tested. These are chosen to ensure that all

standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective I_{OL} and I_{OH} currents shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL ⁽¹⁾	-0.5	0.8	2.0	3.6	0.4	2.4	24	-24
LVC MOS2	-0.5	0.7	1.7	2.7	0.4	1.9	12	-12
LVC MOS18	-0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	$V_{CCO} - 0.4$	8	-8
PCI, 3.3V	-0.5	30% V_{CCO}	50% V_{CCO}	$V_{CCO} + 0.5$	10% V_{CCO}	90% V_{CCO}	Note (2)	Note (2)
GTL	-0.5	$V_{REF} - 0.05$	$V_{REF} + 0.05$	3.6	0.4	-	40	-
GTL+	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.6	-	36	-

IOB Input Delay Adjustments for Different Standards

Input delays associated with the pad are specified for LVTTTL. For other standards, adjust the delays by the values shown. A delay adjusted in this way constitutes a worst-case limit.

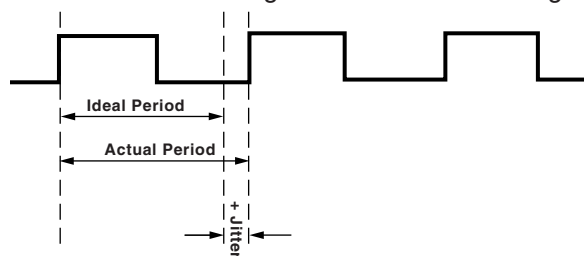
Symbol	Description	Standard	Speed Grade		Units
			-7	-6	
Data Input Delay Adjustments					
T _{ILVTTTL}	Standard-specific data input delay adjustments	LVTTTL	0	0	ns
T _{ILVCMOS2}		LVCMOS2	0	0	ns
T _{ILVCMOS18}		LVCMOS18	0.20	0.20	ns
T _{ILVDS}		LVDS	0.15	0.15	ns
T _{ILVPECL}		LVPECL	0.15	0.15	ns
T _{IPCI33_3}		PCI, 33 MHz, 3.3V	0.08	0.08	ns
T _{IPCI66_3}		PCI, 66 MHz, 3.3V	−0.11	−0.11	ns
T _{IGTL}		GTL	0.14	0.14	ns
T _{IGTLP}		GTL+	0.14	0.14	ns
T _{IHSTL}		HSTL	0.04	0.04	ns
T _{ISSTL2}		SSTL2	0.04	0.04	ns
T _{ISSTL3}		SSTL3	0.04	0.04	ns
T _{ICTT}		CTT	0.10	0.10	ns
T _{IAGP}		AGP	0.04	0.04	ns

Period Tolerance: the allowed input clock period change in nanoseconds.

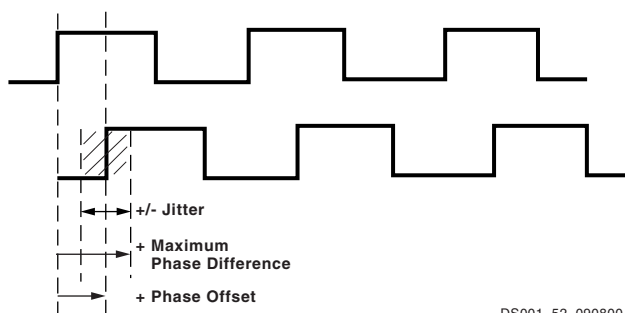
$$T_{CLKIN} = \frac{1}{F_{CLKIN}}$$


The diagram shows a square wave representing a clock signal. Below it, a horizontal line with arrows at both ends is labeled $T_{CLKIN} \pm T_{IPTOL}$, indicating the tolerance range around the nominal period.

Output Jitter: the difference between an ideal reference clock edge and the actual design.



Phase Offset and Maximum Phase Difference



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Figure 22: Period Tolerance and Clock Jitter

CLB Distributed RAM Switching Characteristics

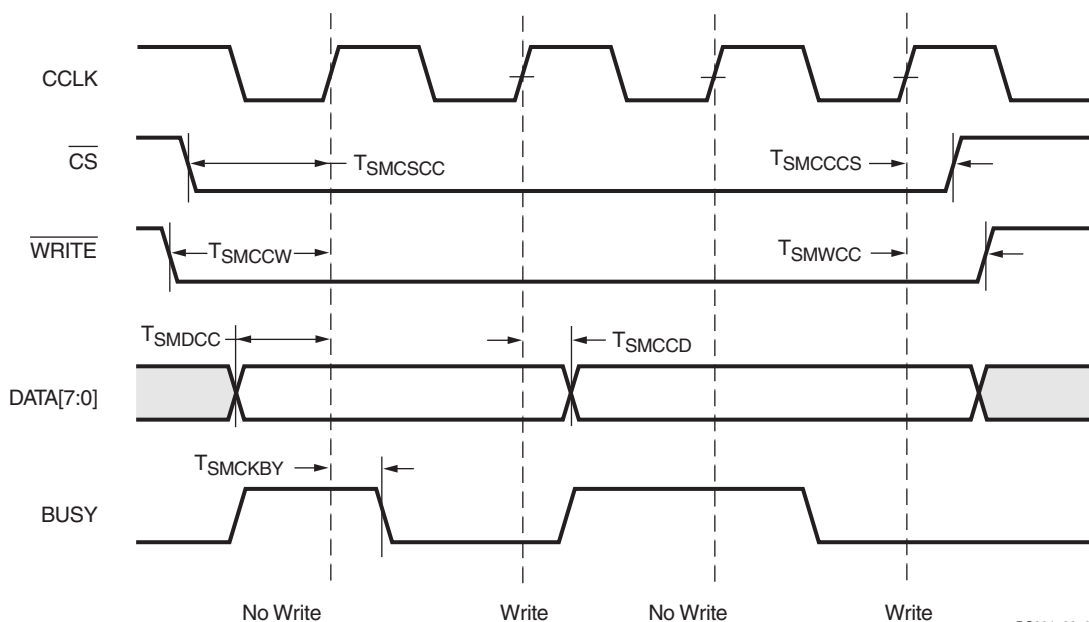
Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T _{SHCKO16}	Clock CLK to X/Y outputs (WE active, 16 x 1 mode)	0.6	1.5	0.6	1.7	ns
T _{SHCKO32}	Clock CLK to X/Y outputs (WE active, 32 x 1 mode)	0.8	1.9	0.8	2.1	ns
Setup/Hold Times with Respect to Clock CLK						
T _{AS} / T _{AH}	F/G address inputs	0.42 / 0	-	0.5 / 0	-	ns
T _{DS} / T _{DH}	BX/BY data inputs (DIN)	0.53 / 0	-	0.6 / 0	-	ns
T _{WS} / T _{WH}	CE input (WS)	0.7 / 0	-	0.8 / 0	-	ns
Clock CLK						
T _{WPH}	Pulse width, High	2.1	-	2.4	-	ns
T _{WPL}	Pulse width, Low	2.1	-	2.4	-	ns
T _{WC}	Clock period to meet address write cycle time	4.2	-	4.8	-	ns

CLB Shift Register Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T _{REG}	Clock CLK to X/Y outputs	1.2	2.9	1.2	3.2	ns
Setup/Hold Times with Respect to Clock CLK						
T _{SHDICK}	BX/BY data inputs (DIN)	0.53 / 0	-	0.6 / 0	-	ns
T _{SHCECK}	CE input (WS)	0.7 / 0	-	0.8 / 0	-	ns
Clock CLK						
T _{SRPH}	Pulse width, High	2.1	-	2.4	-	ns
T _{SRPL}	Pulse width, Low	2.1	-	2.4	-	ns

Block RAM Switching Characteristics

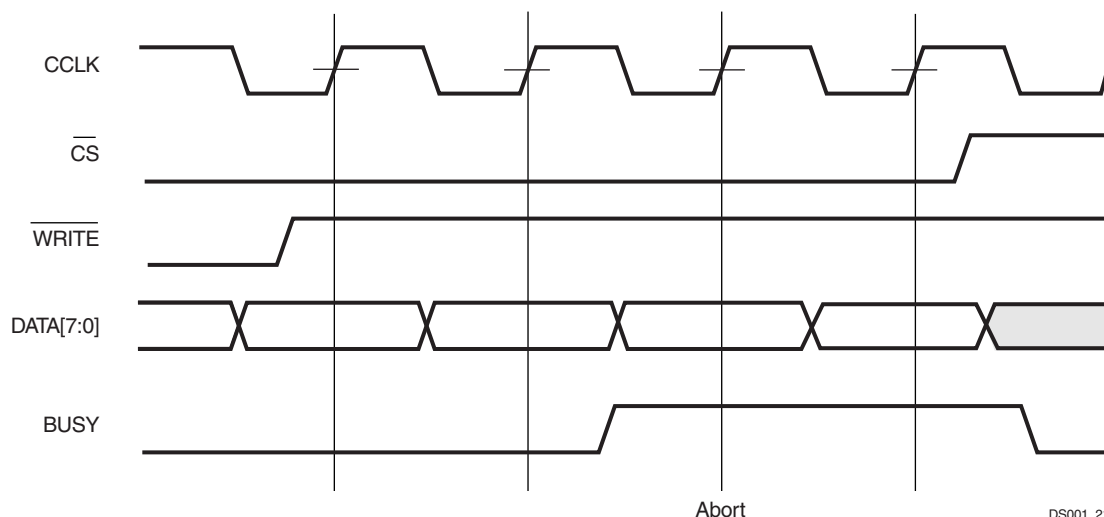
Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T _{BCKO}	Clock CLK to DOUT output	0.6	3.1	0.6	3.5	ns
Setup/Hold Times with Respect to Clock CLK						
T _{BACK} / T _{BCKA}	ADDR inputs	1.0 / 0	-	1.1 / 0	-	ns
T _{BDCK} / T _{BCKD}	DIN inputs	1.0 / 0	-	1.1 / 0	-	ns
T _{BECK} / T _{BCKE}	EN inputs	2.2 / 0	-	2.5 / 0	-	ns
T _{BRCK} / T _{BCKR}	RST input	2.1 / 0	-	2.3 / 0	-	ns
T _{BWCK} / T _{BCKW}	WEN input	2.0 / 0	-	2.2 / 0	-	ns
Clock CLK						
T _{BPWH}	Pulse width, High	1.4	-	1.5	-	ns
T _{BPWL}	Pulse width, Low	1.4	-	1.5	-	ns
T _{BCCS}	CLKA -> CLKB setup time for different ports	2.7	-	3.0	-	ns



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Symbol		Description	All Devices		Units
			Min	Max	
T_{SMDCC} / T_{SMCCD}	CCLK	D0-D7 setup/hold	5 / 1	-	ns
T_{SMCSCC} / T_{SMCCCS}		$\overline{CS}$ setup/hold	7 / 1	-	ns
T_{SMCCW} / T_{SMWCC}		$\overline{WRITE}$ setup/hold	7 / 1	-	ns
T_{SMCKBY}		BUSY propagation delay	-	12	ns
F_{CC}		Frequency	-	66	MHz
F_{CCNH}		Frequency with no handshake	-	50	MHz

Figure 26: Slave Parallel (SelectMAP) Mode Write Timing



DS001_21_032300

Figure 27: Slave Parallel (SelectMAP) Mode Write Abort Waveforms

Low Voltage Differential Signals (LVDS and LVPECL)

The Spartan-IIe family features low-voltage differential signaling (LVDS and LVPECL). Each signal utilizes two pins on the Spartan-IIe device, known as differential pin pairs. Each differential pin pair has a Positive (P) and a Negative (N) pin. These pairs are labeled in the following manner.

I/O, L#[P/N][/_Y/_YY]

where

L = LVDS or LVPECL pin

= Pin pair number

P = Positive

N = Negative

_Y = Asynchronous output allowed (device-dependent)

_YY = Asynchronous output allowed (all devices)

Available Differential Pairs According to Package Type

Device	TQ144	PQ208	FT256	FG456	FG676
XC2S50E	28	50	83	-	-
XC2S100E	28	50	83	86	-
XC2S150E	-	50	83	114	-
XC2S200E	-	50	83	120	-
XC2S300E	-	50	83	120	-
XC2S400E	-	-	83	120	172
XC2S600E	-	-	-	120	205

Synchronous or Asynchronous

I/O pins for differential signals can either be synchronous or asynchronous, input or output. Differential signaling requires the pins of each pair to switch simultaneously. If the output signals driving the pins are from IOB flip-flops, they are synchronous. If the signals driving the pins are from internal logic, they are asynchronous, and therefore more care must be taken that they are simultaneous. Any differential pairs can be used for synchronous input and output signals as well as asynchronous input signals.

However, only the differential pairs with the _Y or _YY suffix can be used for asynchronous output signals.

Asynchronous Output Pad Name Designation

Because of differences between densities, the differential pairs that can be used for asynchronous outputs vary by device. The pairs that are available in all densities for a given package have the _YY suffix. These pins should be used for differential asynchronous outputs if the design may later move to a different density. All other differential pairs that can be used for asynchronous outputs have the _Y suffix.

To simplify the following tables, the "Pad Name" column shows the part of the name that is common across densities. The "Pad Name" column leaves out the _Y suffix and the "LVDS Asynchronous Output Option" column indicates the densities that allow asynchronous outputs for LVDS or LVPECL on the given pin.

DLL Pins

Pins labeled "I/O (DLL)" can be used as general-purpose I/O or as inputs to the DLL. Adjacent DLL pins form a differential pair. They reside in two different banks, so if they are outputs the V_{CCO} level must be the same for both banks. Each DLL pin can also be paired with the adjacent GCK clock pin for a differential clock input. The "I/O (DLL)" pin always becomes the N terminal when paired with GCK, even if it is labeled "P" for its pairing with the adjacent DLL pin.

VREF Pins

Pins labeled "I/O, VREF" can be used as either an I/O or a VREF pin. If any I/O pin within the bank requires a VREF input, all the VREF pins in the bank must be connected to the same voltage. See the I/O banking rules in the [Functional Description](#) module for more detail. If no pin in a given bank requires VREF, then that bank's VREF pins can be used as general I/O.

To simplify the following tables, the "Pad Name" column shows the part of the name that is common across densities. When VREF is only available in limited densities, the "Pad Name" column leaves out the VREF designation and the "VREF Option" column indicates the densities that provide VREF on the given pin.

VCCO Banks

In the TQ144 and PQ208 packages, the eight banks have VCCO connected together. Thus, only one VCCO is allowed in these packages, although different VREF values are allowed in each of the eight banks. See [I/O Banking](#).

PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option
Function	Bank			
I/O, VREF Bank 6, L39P	6	P45	XC2S100E, 150E	All
I/O, L39N	6	P46	XC2S100E, 150E	-
I/O	6	P47	-	XC2S200E, 300E
I/O, L38P_YY	6	P48	All	-
I/O, L38N_YY	6	P49	All	-
M1	-	P50	-	-
GND	-	P51	-	-
M0	-	P52	-	-
VCCO	-	P53	-	-
M2	-	P54	-	-
I/O, L37N_YY	5	P55	All	-
I/O, L37P_YY	5	P56	All	-
I/O	5	P57	-	XC2S200E, 300E
I/O	5	P58	-	-
I/O, VREF Bank 5, L36N_YY	5	P59	All	All
I/O, L36P_YY	5	P60	All	-
I/O, L35N	5	P61	XC2S50E, 100E, 300E	-
I/O, L35P	5	P62	XC2S50E, 100E, 300E	-
I/O, L34N	5	P63	XC2S50E, 100E, 200E, 300E	XC2S100E, 150E, 200E, 300E
I/O, L34P	5	P64	XC2S50E, 100E, 200E, 300E	-
GND	-	P65	-	-

PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option
Function	Bank			
VCCO	-	P66	-	-
VCCINT	-	P67	-	-
I/O, L33N	5	P68	XC2S50E, 100E, 200E, 300E	-
I/O, L33P	5	P69	XC2S50E, 100E, 200E, 300E	-
I/O	5	P70	-	-
I/O, L32N	5	P71	XC2S100E, 150E	-
GND	-	P72	-	-
I/O, VREF Bank 5, L32P	5	P73	XC2S100E, 150E	All
I/O	5	P74	-	-
I/O (DLL), L31N	5	P75	-	-
VCCINT	-	P76	-	-
GCK1, I	5	P77	-	-
VCCO	-	P78	-	-
GND	-	P79	-	-
GCK0, I	4	P80	-	-
I/O (DLL), L31P	4	P81	-	-
I/O	4	P82	-	-
I/O, L30N	4	P83	XC2S50E, 200E, 300E	-
I/O, VREF Bank 4, L30P	4	P84	XC2S50E, 200E, 300E	All
GND	-	P85	-	-
I/O, L29N	4	P86	XC2S50E, 200E, 300E	-
I/O, L29P	4	P87	XC2S50E, 200E, 300E	-
I/O, L28N	4	P88	XC2S50E, 100E, 200E, 300E	-

PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option
Function	Bank			
I/O	2	P134	-	-
I/O (D3), L17N	2	P135	XC2S50E, 300E	-
I/O, VREF Bank 2, L17P	2	P136	XC2S50E, 300E	All
GND	-	P137	-	-
I/O, L16N_YY	2	P138	All	-
I/O, L16P_YY	2	P139	All	-
I/O, L15N_YY	2	P140	All	-
I/O (D2), L15P_YY	2	P141	All	-
VCCINT	-	P142	-	-
VCCO	-	P143	-	-
GND	-	P144	-	-
I/O (D1), L14N	2	P145	XC2S50E, 300E	-
I/O, L14P	2	P146	XC2S50E, 300E	XC2S100E, 150E, 200E, 300E
I/O	2	P147	-	-
I/O	2	P148	-	-
I/O	2	P149	-	-
I/O, VREF Bank 2, L13N	2	P150	XC2S100E, 150E	All
I/O, L13P	2	P151	XC2S100E, 150E	-
I/O	2	P152	-	XC2S200E, 300E
I/O (DIN, D0), L12N_YY	2	P153	All	-
I/O (DOUT, BUSY), L12P_YY	2	P154	All	-
CCLK	2	P155	-	-

PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option
Function	Bank			
VCCO	-	P156	-	-
TDO	2	P157	-	-
GND	-	P158	-	-
TDI	-	P159	-	-
I/O ($\overline{CS}$), L11P_YY	1	P160	All	-
I/O ($\overline{WRITE}$), L11N_YY	1	P161	All	-
I/O	1	P162	-	XC2S200E, 300E
I/O	1	P163	-	-
I/O, VREF Bank 1, L10P_YY	1	P164	All	All
I/O, L10N_YY	1	P165	All	-
I/O	1	P166	-	-
I/O	1	P167	-	-
I/O, L9P	1	P168	XC2S50E, 100E, 200E, 300E	XC2S100E, 150E, 200E, 300E
I/O, L9N	1	P169	XC2S50E, 100E, 200E, 300E	-
GND	-	P170	-	-
VCCO	-	P171	-	-
VCCINT	-	P172	-	-
I/O, L8P	1	P173	XC2S50E, 100E, 200E, 300E	-
I/O, L8N	1	P174	XC2S50E, 100E, 200E, 300E	-
I/O, L7P	1	P175	XC2S50E, 200E, 300E	-
I/O, L7N	1	P176	XC2S50E, 200E, 300E	-
GND	-	P177	-	-

FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option	Device-Specific Pinouts: XC2S					
Function	Bank				100E	150E	200E	300E	400E	600E
I/O	7	H5	-	-	-	-	-	I/O	I/O	I/O
I/O, VREF Bank 7, L#P_Y	7	H3	XC2S300E, 400E, 600E	All	I/O, VREF Bank 7, L81P	I/O, VREF Bank 7, L106P	I/O, VREF Bank 7, L113P	I/O, VREF Bank 7, L113P_Y	I/O, VREF Bank 7, L113P_Y	I/O, VREF Bank 7, L113P_Y
I/O, L#N_Y	7	H4	XC2S300E, 400E, 600E	-	I/O, L81N	I/O, L106N	I/O, L113N	I/O, L113N_Y	I/O, L113N_Y	I/O, L113N_Y
I/O, L#P_YY	7	H2	All	-	I/O, L80P_YY	I/O, L105P_YY	I/O, L112P_YY	I/O, L112P_YY	I/O, L112P_YY	I/O, L112P_YY
I/O, L#N_YY	7	H1	All	-	I/O, L80N_YY	I/O, L105N_YY	I/O, L112N_YY	I/O, L112N_YY	I/O, L112N_YY	I/O, L112N_YY
I/O	7	J6	-	-	-	-	I/O	I/O	I/O	I/O
I/O, L#P_Y	7	J4	XC2S150E, 200E, 300E, 400E	-	-	I/O, L104P_Y	I/O, L111P_Y	I/O, L111P_Y	I/O, L111P_Y	I/O, L111P
I/O, L#N_Y	7	J5	XC2S100E, 150E, 200E, 300E, 400E	-	I/O, L79P_Y	I/O, L104N_Y	I/O, L111N_Y	I/O, L111N_Y	I/O, L111N_Y	I/O, L111N
I/O, L#P_Y	7	J3	XC2S100E, 150E, 200E, 300E, 600E	-	I/O, L79N_Y	I/O, L103P_Y	I/O, L110P_Y	I/O, L110P_Y	I/O, L110P	I/O, L110P_Y
I/O, L#N_Y	7	J2	XC2S150E, 200E, 300E, 600E	-	-	I/O, L103N_Y	I/O, L110N_Y	I/O, L110N_Y	I/O, L110N	I/O, L110N_Y
I/O	7	J1	-	-	-	-	I/O	I/O	I/O	I/O
I/O, L#P	7	K5	XC2S100E, 150E, 200E, 300E, 600E ⁽¹⁾	-	I/O, L78P_YY	I/O, L102P_YY	I/O, L109P_YY	I/O, L109P_YY	I/O, L109P	I/O, L109P_Y
I/O, L#N	7	K6	XC2S100E, 150E, 200E, 300E, 600E ⁽¹⁾	-	I/O, L78N_YY	I/O, L102N_YY	I/O, L109N_YY	I/O, L109N_YY	I/O, L109N	I/O, L109N_Y
I/O, VREF Bank 7, L#P_Y	7	K3	XC2S300E, 400E, 600E	All	I/O, VREF Bank 7, L77P	I/O, VREF Bank 7, L101P	I/O, VREF Bank 7, L108P	I/O, VREF Bank 7, L108P_Y	I/O, VREF Bank 7, L108P_Y	I/O, VREF Bank 7, L108P_Y
I/O, L#N_Y	7	K4	XC2S300E, 400E, 600E	-	I/O, L77N	I/O, L101N	I/O, L108N	I/O, L108N_Y	I/O, L108N_Y	I/O, L108N_Y
I/O	7	K2	-	-	-	-	-	I/O	I/O	I/O
I/O, L#P_Y	7	K1	XC2S300E, 400E	-	-	-	I/O, L107P	I/O, L107P_Y	I/O, L107P_Y	I/O, L107P
I/O, L#N_Y	7	L1	XC2S100E, 150E, 300E, 400E	-	I/O, L76P_Y	I/O, L100P_Y	I/O, L107N	I/O, L107N_Y	I/O, L107N_Y	I/O, L107N
I/O, L#P_Y	7	L3	XC2S100E, 150E, 200E, 300E, 600E	XC2S400E, 600E	I/O, L76N_Y	I/O, L100N_Y	I/O, L106P_Y	I/O, L106P_Y	I/O, VREF Bank 7, L106P	I/O, VREF Bank 7, L106P_Y
I/O, L#N_Y	7	L2	XC2S200E, 300E, 600E	-	-	I/O	I/O, L106N_Y	I/O, L106N_Y	I/O, L106N	I/O, L106N_Y
I/O	7	L4	-	-	-	-	-	I/O	I/O	I/O

FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option	Device-Specific Pinouts: XC2S					
Function	Bank				100E	150E	200E	300E	400E	600E
I/O, L#P_YY	7	L5	All	-	I/O, L75P_YY	I/O, L99P_YY	I/O, L105P_YY	I/O, L105P_YY	I/O, L105P_YY	I/O, L105P_YY
I/O (IRDY), L#N_YY	7	L6	All	-	I/O (IRDY), L75N_YY	I/O (IRDY), L99N_YY	I/O (IRDY), L105N_YY	I/O (IRDY), L105N_YY	I/O (IRDY), L105N_YY	I/O (IRDY), L105N_YY
I/O (TRDY)	6	M1	-	-	I/O (TRDY)	I/O (TRDY)	I/O (TRDY)	I/O (TRDY)	I/O (TRDY)	I/O (TRDY)
I/O	6	M2	-	-	-	-	-	I/O	I/O	I/O
I/O, L#P_Y	6	M3	XC2S200E, 300E, 600E	-	-	I/O	I/O, L104P_Y	I/O, L104P_Y	I/O, L104P	I/O, L104P_Y
I/O, L#N_Y	6	M4	XC2S100E, 150E, 200E, 300E, 600E	XC2S400E, 600E	I/O, L74P_Y	I/O, L98P_Y	I/O, L104N_Y	I/O, L104N_Y	I/O, VREF Bank 6, L104N	I/O, VREF Bank 6, L104N_Y
I/O, L#P_Y	6	M5	XC2S100E, 150E, 300E, 400E	-	I/O, L74N_Y	I/O, L98N_Y	I/O, L103P	I/O, L103P_Y	I/O, L103P_Y	I/O, L103P
I/O, L#N_Y	6	M6	XC2S300E, 400E	-	-	-	I/O, L103N	I/O, L103N_Y	I/O, L103N_Y	I/O, L103N
I/O	6	N1	-	-	-	-	-	I/O	I/O	I/O
I/O	6	N2	-	-	I/O, L73P	I/O, L97P	I/O	I/O	I/O	I/O
I/O, VREF Bank 6, L#P	6	N3	XC2S200E, 400E	All	I/O, VREF Bank 6, L73N	I/O, VREF Bank 6, L97N	I/O, VREF Bank 6, L102P_Y	I/O, VREF Bank 6, L102P	I/O, VREF Bank 6, L102P_Y	I/O, VREF Bank 6, L102P
I/O, L#N	6	N4	XC2S100E, 150E, 200E, 400E	-	I/O, L72P_Y	I/O, L96P_Y	I/O, L102N_Y	I/O, L102N	I/O, L102N_Y	I/O, L102N
I/O, L#P_Y	6	N5	XC2S100E, 150E, 300E, 600E	-	I/O, L72N_Y	I/O, L96N_Y	I/O, L101P	I/O, L101P_Y	I/O, L101P	I/O, L101P_Y
I/O, L#N_Y	6	N6	XC2S300E, 600E	-	-	-	I/O, L101N	I/O, L101N_Y	I/O, L101N	I/O, L101N_Y
I/O, L#P_Y	6	P1	XC2S150E, 200E, 300E, 600E	-	-	I/O, L95P_Y	I/O, L100P_Y	I/O, L100P_Y	I/O, L100P	I/O, L100P_Y
I/O, L#N_Y	6	P2	XC2S100E, 150E, 200E, 300E, 600E	-	I/O, L71P_Y	I/O, L95N_Y	I/O, L100N_Y	I/O, L100N_Y	I/O, L100N	I/O, L100N_Y
I/O	6	R1	XC2S100E, 150E	-	I/O, L71N_Y	I/O, L94P_Y	I/O	I/O	I/O	I/O
I/O, L#P_Y	6	P3	XC2S150E, 200E, 300E, 400E, 600E	-	-	I/O, L94N_Y	I/O, L99P_Y	I/O, L99P_Y	I/O, L99P_Y	I/O, L99P_Y
I/O, L#N_Y	6	P4	XC2S200E, 300E, 400E, 600E	-	-	-	I/O, L99N_Y	I/O, L99N_Y	I/O, L99N_Y	I/O, L99N_Y
I/O, L#P_YY	6	P5	All	-	I/O, L70P_YY	I/O, L93P_YY	I/O, L98P_YY	I/O, L98P_YY	I/O, L98P_YY	I/O, L98P_YY
I/O, L#N_YY	6	P6	All	-	I/O, L70N_YY	I/O, L93N_YY	I/O, L98N_YY	I/O, L98N_YY	I/O, L98N_YY	I/O, L98N_YY

FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option	Device-Specific Pinouts: XC2S					
Function	Bank				100E	150E	200E	300E	400E	600E
I/O, VREF Bank 5, L#N_Y	5	V8	XC2S100E, 200E, 300E, 400E, 600E	All	I/O, VREF Bank 5, L58N_Y	I/O, VREF Bank 5, L77N	I/O, VREF Bank 5, L82N_Y	I/O, VREF Bank 5, L82N_Y	I/O, VREF Bank 5, L82N_Y	I/O, VREF Bank 5, L82N_Y
I/O, L#P_Y	5	W8	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L58P_Y	I/O, L77P	I/O, L82P_Y	I/O, L82P_Y	I/O, L82P_Y	I/O, L82P_Y
I/O, L#N_Y	5	AB9	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L57N_Y	I/O, L76N	I/O, L81N_Y	I/O, L81N_Y	I/O, L81N_Y	I/O, L81N_Y
I/O, L#P_Y	5	AA9	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L57P_Y	I/O, L76P	I/O, L81P_Y	I/O, L81P_Y	I/O, L81P_Y	I/O, L81P_Y
I/O	5	AB10	-	-	-	-	I/O	I/O	I/O	I/O
I/O, L#N_Y	5	W9	XC2S150E, 300E, 400E, 600E	-	-	I/O, L75N_Y	I/O, L80N	I/O, L80N_Y	I/O, L80N_Y	I/O, L80N_Y
I/O, L#P_Y	5	Y9	XC2S100E, 150E, 300E, 400E, 600E	-	I/O, L56N_Y	I/O, L75P_Y	I/O, L80P	I/O, L80P_Y	I/O, L80P_Y	I/O, L80P_Y
I/O, L#N_Y	5	V9	XC2S100E, 150E, 300E, 400E, 600E	-	I/O, L56P_Y	I/O, L74N_Y	I/O, L79N	I/O, L79N_Y	I/O, L79N_Y	I/O, L79N_Y
I/O, L#P_Y	5	U9	XC2S150E, 300E, 400E, 600E	-	-	I/O, L74P_Y	I/O, L79P	I/O, L79P_Y	I/O, L79P_Y	I/O, L79P_Y
I/O	5	AA10	-	-	-	-	I/O	I/O	I/O	I/O
I/O, L#N_Y	5	W10	XC2S200E, 300E, 400E, 600E	-	I/O, L55N	I/O, L73N	I/O, L78N_Y	I/O, L78N_Y	I/O, L78N_Y	I/O, L78N_Y
I/O, L#P_Y	5	Y10	XC2S200E, 300E, 400E, 600E	-	I/O, L55P	I/O, L73P	I/O, L78P_Y	I/O, L78P_Y	I/O, L78P_Y	I/O, L78P_Y
I/O, VREF Bank 5, L#N_Y	5	V10	XC2S200E, 300E, 400E, 600E	All	I/O, VREF Bank 5, L54N	I/O, VREF Bank 5, L72N	I/O, VREF Bank 5, L77N_Y	I/O, VREF Bank 5, L77N_Y	I/O, VREF Bank 5, L77N_Y	I/O, VREF Bank 5, L77N_Y
I/O, L#P_Y	5	U10	XC2S200E, 300E, 400E, 600E	-	I/O, L54P	I/O, L72P	I/O, L77P_Y	I/O, L77P_Y	I/O, L77P_Y	I/O, L77P_Y
I/O	5	U11	-	-	-	-	-	I/O	I/O	I/O
I/O	5	V11	-	-	-	-	I/O	I/O	I/O	I/O
I/O, L#N	5	W11	XC2S200E, 400E	-	I/O	I/O, L71N	I/O, L76N_Y	I/O, L76N	I/O, L76N_Y	I/O, L76N
I/O, L#P	5	Y11	XC2S200E, 400E	XC2S400E, 600E	-	I/O, L71P	I/O, L76P_Y	I/O, L76P	I/O, VREF Bank 5, L76P_Y	I/O, VREF Bank 5, L76P
I/O	5	AA11	-	-	-	-	-	I/O	I/O	I/O
I/O (DLL), L#N	5	AB11	-	-	I/O (DLL), L53N	I/O (DLL), L70N	I/O (DLL), L75N	I/O (DLL), L75N	I/O (DLL), L75N	I/O (DLL), L75N
GCK1, I	5	AB12	-	-	GCK1, I	GCK1, I	GCK1, I	GCK1, I	GCK1, I	GCK1, I

FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option	Device-Specific Pinouts: XC2S					
Function	Bank				100E	150E	200E	300E	400E	600E
I/O, L#P	2	L17	XC2S100E, 150E, 200E, 300E, 600E	XC2S400E, 600E	I/O, L29N_Y	I/O, L40N_Y	I/O, L43P_Y	I/O, L43P_Y	I/O, VREF Bank 2, L43P	I/O, VREF Bank 2, L43P_Y
I/O, L#N	2	K22	XC2S100E, 150E, 300E, 400E	-	I/O, L29P_Y	I/O, L40P_Y	I/O, L42N	I/O, L42N_Y	I/O, L42N_Y	I/O, L42N
I/O, L#P	2	K21	XC2S300E, 400E	-	-	-	I/O, L42P	I/O, L42P_Y	I/O, L42P_Y	I/O, L42P
I/O	2	K20	-	-	-	-	-	I/O	I/O	I/O
I/O (D3)	2	K19	-	-	I/O (D3)	I/O (D3), L39N	I/O (D3)	I/O (D3)	I/O (D3)	I/O (D3)
I/O, VREF Bank 2, L#N	2	K18	XC2S100E, 200E, 400E	All	I/O, VREF Bank 2, L28N_Y	I/O, VREF Bank 2, L39P	I/O, VREF Bank 2, L41N_Y	I/O, VREF Bank 2, L41N	I/O, VREF Bank 2, L41N_Y	I/O, VREF Bank 2, L41N
I/O, L#P	2	K17	XC2S100, 150E, 200E, 400E	-	I/O, L28P_Y	I/O, L38N_Y	I/O, L41P_Y	I/O, L41P	I/O, L41P_Y	I/O, L41P
I/O, L#N	2	J22	XC2S150E, 300E, 600E	-	I/O	I/O, L38P_Y	I/O, L40N	I/O, L40N_Y	I/O, L40N	I/O, L40N_Y
I/O, L#P	2	J21	XC2S300E, 600E	-	-	-	I/O, L40P	I/O, L40P_Y	I/O, L40P	I/O, L40P_Y
I/O, L#N	2	J20	XC2S150E, 200E, 300E, 600E	-	-	I/O, L37N_Y	I/O, L39N_Y	I/O, L39N_Y	I/O, L39N	I/O, L39N_Y
I/O, L#P	2	J19	XC2S100E, 150E, 200E, 300E, 600E	-	I/O, L27N_Y	I/O, L37P_Y	I/O, L39P_Y	I/O, L39P_Y	I/O, L39P	I/O, L39P_Y
I/O	2	H22	XC2S100E, 150E	-	I/O, L27P_Y	I/O, L36N_Y	I/O	I/O	I/O	I/O
I/O, L#N	2	J18	XC2S150E, 200E, 300E, 400E, 600E	-	-	I/O, L36P_Y	I/O, L38N_Y	I/O, L38N_Y	I/O, L38N_Y	I/O, L38N_Y
I/O, L#P	2	J17	XC2S200E, 300E, 400E, 600E	-	-	-	I/O, L38P_Y	I/O, L38P_Y	I/O, L38P_Y	I/O, L38P_Y
I/O, L#N	2	H21	XC2S150E, 200E, 300E, 400E, 600E	-	I/O	I/O, L35N_Y	I/O, L37N_Y	I/O, L37N_Y	I/O, L37N_Y	I/O, L37N_Y
I/O (D2), L#P	2	H20	XC2S150E, 200E, 300E, 400E, 600E	-	I/O (D2)	I/O (D2), L35P_Y	I/O (D2), L37P_Y	I/O (D2), L37P_Y	I/O (D2), L37P_Y	I/O (D2), L37P_Y
I/O (D1), L#N	2	H19	XC2S300E, 400E, 600E	-	I/O (D1), L26N	I/O (D1), L34N	I/O (D1), L36N	I/O (D1), L36N_Y	I/O (D1), L36N_Y	I/O (D1), L36N_Y
I/O, VREF Bank 2, L#P	2	H18	XC2S300E, 400E, 600E	All	I/O, VREF Bank 2, L26P	I/O, VREF Bank 2, L34P	I/O, VREF Bank 2, L36P	I/O, VREF Bank 2, L36P_Y	I/O, VREF Bank 2, L36P_Y	I/O, VREF Bank 2, L36P_Y
I/O	2	G22	-	-	-	-	-	I/O	I/O	I/O
I/O	2	F22	-	-	I/O	I/O	I/O	I/O	I/O	I/O

FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)

Pad Name		Pin	LVDS Async. Output Option	V _{REF} Option	Device-Specific Pinouts: XC2S					
Function	Bank				100E	150E	200E	300E	400E	600E
I/O, L#P_YY	0	A6	All	-	I/O, L2P_YY	I/O, L3P_YY	I/O, L3P_YY	I/O, L3P_YY	I/O, L3P_YY	I/O, L3P_YY
I/O, VREF Bank 0, L#N_YY	0	B6	All	All	I/O, VREF Bank 0, L2N_YY	I/O, VREF Bank 0, L3N_YY	I/O, VREF Bank 0, L3N_YY	I/O, VREF Bank 0, L3N_YY	I/O, VREF Bank 0, L3N_YY	I/O, VREF Bank 0, L3N_YY
I/O	0	C6	XC2S100E	-	I/O, L1P_Y	I/O	I/O	I/O	I/O	I/O
I/O, L#P	0	A5	XC2S100E	-	I/O, L1N_Y	I/O, L2P	I/O, L2P	I/O, L2P	I/O, L2P	I/O, L2P
I/O, L#N	0	B5	-	-	-	I/O, L2N	I/O, L2N	I/O, L2N	I/O, L2N	I/O, L2N
I/O	0	D6	-	-	-	-	-	I/O	I/O	I/O
I/O, L#P	0	B4	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L0P_Y	I/O, L1P	I/O, L1P_Y	I/O, L1P_Y	I/O, L1P_Y	I/O, L1P_Y
I/O, L#N	0	C5	XC2S100E, 200E, 300E, 400E, 600E	XC2S200E, 300E, 400E, 600E	I/O, L0N_Y	I/O, L1N	I/O, VREF Bank 0, L1N_Y	I/O, VREF Bank 0, L1N_Y	I/O, VREF Bank 0, L1N_Y	I/O, VREF Bank 0, L1N_Y
I/O	0	A4	-	-	I/O	I/O	I/O	I/O	I/O	I/O
I/O, L#P	0	A3	XC2S150E, 400E, 600E	-	-	I/O, L0P_Y	I/O, L0P	I/O, L0P	I/O, L0P_Y	I/O, L0P_Y
I/O, L#N	0	B3	XC2S150E, 400E, 600E	-	-	I/O, L0N_Y	I/O, L0N	I/O, L0N	I/O, L0N_Y	I/O, L0N_Y
I/O	0	C4	-	-	-	-	-	I/O	I/O	I/O
I/O	0	D5	-	-	I/O	I/O	I/O	I/O	I/O	I/O
TCK	-	E6	-	-	TCK	TCK	TCK	TCK	TCK	TCK

Notes:

- Although designated with the _YY suffix in the XC2S100E, XC2S150E, XC2S200E, and XC2S300E, these differential pairs are not asynchronous in the XC2S400E.

FG456 Differential Clock Pins

Clock	Bank	P		N	
		Pin	Name	Pin	Name
GCK0	4	AA12	GCK0, I	Y12	I/O (DLL), L#P
GCK1	5	AB12	GCK1, I	AB11	I/O (DLL), L#N
GCK2	1	A11	GCK2, I	A12	I/O (DLL), L#P
GCK3	0	C11	GCK3, I	B11	I/O (DLL), L#N

Additional FG456 Package Pins

VCCINT Pins								
D4 ⁽¹⁾	D19 ⁽¹⁾	E5	E18	F6	F17	G7	G8	G15
G16	H7	H16	R7	R16	T7	T8	T15	T16
U6	U17	V5	V18	W4 ⁽¹⁾	W19 ⁽¹⁾	-	-	-
VCCO Bank 0 Pins								
F7	F8	G9	G10	-	-	-	-	-

Additional FG456 Package Pins (Continued)

VCCO Bank 1 Pins								
F15	F16	G13	G14	-	-	-	-	-
VCCO Bank 2 Pins								
G17	H17	J16	K16	-	-	-	-	-
VCCO Bank 3 Pins								
N16	P16	R17	T17	-	-	-	-	-
VCCO Bank 4 Pins								
T13	T14	U15	U16	-	-	-	-	-
VCCO Bank 5 Pins								
T9	T10	U7	U8	-	-	-	-	-
VCCO Bank 6 Pins								
N7	P7	R6	T6	-	-	-	-	-
VCCO Bank 7 Pins								
G6	H6	J7	K7	-	-	-	-	-
GND Pins								
A1	A2 ⁽²⁾	A22	B1 ⁽²⁾	B2	B21	C3	C20	G11
G12	J9	J10	J11	J12	J13	J14	K9	K10
K11	K12	K13	K14	L7	L9	L10	L11	L12
L13	L14	L16	M7	M9	M10	M11	M12	M13
M14	M16	N9	N10	N11	N12	N13	N14	P9
P10	P11	P12	P13	P14	T11	T12	Y20	Y3
Y4 ⁽²⁾	AA2	AA4 ⁽²⁾	AA21	AA22 ⁽²⁾	AB1	AB22	-	-
Not Connected Pins								
A2 ⁽²⁾	B1 ⁽²⁾	D4 ⁽¹⁾	D19 ⁽¹⁾	W4 ⁽¹⁾	W19 ⁽¹⁾	Y4 ⁽²⁾	AA4 ⁽²⁾	AA22 ⁽²⁾

Notes:

- VCCINT connections in XC2S400E and XC2S600E. No Connects (no internal connection) in XC2S100E, XC2S150E, XC2S200E, and XC2S300E.
- GND connections in XC2S400E and XC2S600E. No Connects (no internal connection) in XC2S100E, XC2S150E, XC2S200E, and XC2S300E.

FG676 Pinouts (XC2S400E, XC2S600E)

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
TMS	-	B1	-	-	TMS	TMS
I/O	7	D3	-	-	I/O	I/O
I/O, L204P	7	C2	-	-	-	I/O, L204P
I/O, L204N	7	C1	-	-	-	I/O, L204N
I/O, L203P	7	D2	XC2S600E	-	-	I/O, L203P_Y
I/O, L203N	7	D1	XC2S600E	-	I/O	I/O, L203N_Y
I/O, L202P_YY	7	E2	All	-	I/O, L202P_YY	I/O, L202P_YY
I/O, L202N_YY	7	E1	All	-	I/O, L202N_YY	I/O, L202N_YY

FG676 Pinouts (XC2S400E, XC2S600E) (Continued)

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O	5	AC5	-	-	I/O	I/O
I/O, L152N	5	AE4	-	-	I/O	I/O, L152N
I/O, L152P	5	AF4	-	-	-	I/O, L152P
I/O, L151N	5	AE5	-	-	-	I/O, L151N
I/O, L151P	5	AF5	-	-	I/O	I/O, L151P
I/O, L150N	5	AA6	XC2S400E	-	I/O, L150N_Y	I/O, L150N
I/O, L150P	5	AB6	XC2S400E	-	I/O, L150P_Y	I/O, L150P
I/O, L149N_YY	5	AC6	All	-	I/O, L149N_YY	I/O, L149N_YY
I/O, L149P_YY	5	AD6	All	-	I/O, L149P_YY	I/O, L149P_YY
I/O, VREF Bank 5, L148N_YY	5	AE6	All	All	I/O, VREF Bank 5, L148N_YY	I/O, VREF Bank 5, L148N_YY
I/O, L148P_YY	5	AF6	All	-	I/O, L148P_YY	I/O, L148P_YY
I/O, L147N	5	AA7	XC2S600E	-	-	I/O, L147N_Y
I/O, L147P	5	AB7	XC2S600E	-	I/O	I/O, L147P_Y
I/O, L146N_YY	5	AC7	All	-	I/O, L146N_YY	I/O, L146N_YY
I/O, L146P_YY	5	AD7	All	-	I/O, L146P_YY	I/O, L146P_YY
I/O, L145N_YY	5	AE7	All	-	I/O, L145N_YY	I/O, L145N_YY
I/O, L145P_YY	5	AF7	All	-	I/O, L145P_YY	I/O, L145P_YY
I/O, VREF Bank 5, L144N_YY	5	Y8	All	All	I/O, VREF Bank 5, L144N_YY	I/O, VREF Bank 5, L144N_YY
I/O, L144P_YY	5	AA8	All	-	I/O, L144P_YY	I/O, L144P_YY
I/O, L143N_YY	5	AE8	All	-	I/O, L143N_YY	I/O, L143N_YY
I/O, L143P_YY	5	AF8	All	-	I/O, L143P_YY	I/O, L143P_YY
I/O	5	AB8	-	-	I/O	I/O
I/O, L142N	5	W9	XC2S600E	-	I/O, L142N	I/O, L142N_Y
I/O, L142P	5	Y9	XC2S600E	-	I/O, L142P	I/O, L142P_Y
I/O, L141N	5	AA9	XC2S600E	XC2S600E	-	I/O, VREF Bank 5, L141N_Y
I/O, L141P	5	AB9	XC2S600E	-	I/O	I/O, L141P_Y
I/O, L140N_YY	5	AC9	All	-	I/O, L140N_YY	I/O, L140N_YY
I/O, L140P_YY	5	AD9	All	-	I/O, L140P_YY	I/O, L140P_YY
I/O, L139N_YY	5	AE9	All	-	I/O, L139N_YY	I/O, L139N_YY
I/O, L139P_YY	5	AF9	All	-	I/O, L139P_YY	I/O, L139P_YY
I/O, VREF Bank 5, L138N_YY	5	W10	All	All	I/O, VREF Bank 5, L138N_YY	I/O, VREF Bank 5, L138N_YY

FG676 Pinouts (XC2S400E, XC2S600E) (Continued)

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O	4	AC18	-	-	I/O	I/O
I/O, VREF Bank 4, L114N	4	AB18	-	All	I/O, VREF Bank 4, L114N	I/O, VREF Bank 4, L114N
I/O, L114P	4	AA18	-	-	I/O, L114P	I/O, L114P
I/O, L113N	4	Y18	-	-	I/O, L113N	I/O, L113N
I/O, L113P	4	W18	-	-	I/O, L113P	I/O, L113P
I/O	4	AB19	-	-	I/O	I/O
I/O, L112N	4	AF19	XC2S600E	-	I/O	I/O, L112N_Y
I/O, L112P	4	AE19	XC2S600E	XC2S600E	-	I/O, VREF Bank 4, L112P_Y
I/O, L111N	4	AA19	XC2S600E	-	I/O, L111N	I/O, L111N_Y
I/O, L111P	4	Y19	XC2S600E	-	I/O, L111P	I/O, L111P_Y
I/O	4	AF20	-	-	-	I/O
I/O, L110N	4	AE20	XC2S600E	-	I/O, L110N	I/O, L110N_Y
I/O, L110P	4	AD20	XC2S600E	-	I/O, L110P	I/O, L110P_Y
I/O	4	AC20	-	-	I/O	I/O
I/O, L109N_YY	4	AB20	All	-	I/O, L109N_YY	I/O, L109N_YY
I/O, VREF Bank 4, L109P_YY	4	AA20	All	All	I/O, VREF Bank 4, L109P_YY	I/O, VREF Bank 4, L109P_YY
I/O	4	Y20	-	-	I/O	I/O
I/O, L108N	4	AF21	-	-	I/O, L108N	I/O, L108N
I/O, L108P	4	AE21	-	-	I/O, L108P	I/O, L108P
I/O, L107N	4	AD21	-	-	I/O, L107N	I/O, L107N
I/O, L107P	4	AC21	-	-	I/O, L107P	I/O, L107P
I/O	4	AC22	-	-	-	I/O
I/O, L106N_YY	4	AF22	All	-	I/O, L106N_YY	I/O, L106N_YY
I/O, VREF Bank 4, L106P_YY	4	AE22	All	All	I/O, VREF Bank 4, L106P_YY	I/O, VREF Bank 4, L106P_YY
I/O, L105N_YY	4	AB21	All	-	I/O, L105N_YY	I/O, L105N_YY
I/O, L105P_YY	4	AA21	All	-	I/O, L105P_YY	I/O, L105P_YY
I/O, L104N_YY	4	AF23	All	-	I/O, L104N_YY	I/O, L104N_YY
I/O, L104P_YY	4	AE23	All	-	I/O, L104P_YY	I/O, L104P_YY
I/O, L103N	4	AD23	XC2S600E	-	I/O	I/O, L103N_Y
I/O, L103P	4	AE24	XC2S600E	-	-	I/O, L103P_Y
I/O, L102N_YY	4	AF24	All	-	I/O, L102N_YY	I/O, L102N_YY
I/O, L102P_YY	4	AF25	All	-	I/O, L102P_YY	I/O, L102P_YY

Additional FG676 Package Pins (*Continued*)

GND Pins						
A1	A26	B2	B25	C3	C12	C15
C24	D4	D8	D19	D23	F10	F17
H4	H23	K6	K21	L11	L12	L13
L14	L15	L16	M3	M11	M12	M13
M14	M15	M16	M24	N11	N12	N13
N14	N15	N16	P11	P12	P13	P14
P15	P16	R3	R11	R12	R13	R14
R15	R16	R24	T11	T12	T13	T14
T15	T16	U6	U21	W4	W23	AA10
AA17	AC4	AC8	AC19	AC23	AD3	AD12
AD15	AD24	AE2	AE25	AF1	AF26	-
Not Connected Pins (XC2S400E Only)						
A12	A16	A23	B3	C1	C2	C10
C11	C25	D2	D15	D18	D24	D25
E7	E13	E19	F2	F6	F8	F12
F20	F22	G10	G14	G15	G16	G26
H10	H13	H16	H25	J6	J8	J12
J13	K1	K4	K22	K24	L3	L19
L22	L26	M4	M9	M22	N1	N4
N9	N18	N19	N23	P4	P5	P18
P19	P24	R4	R7	R19	T3	T24
U1	U4	U7	U24	U25	V8	V12
V13	V21	W12	W13	W14	W16	Y3
Y7	Y21	AA7	AA9	AA22	AB15	AB16
AB17	AB22	AC1	AC15	AC22	AC25	AC26
AD1	AD2	AD10	AD11	AD13	AD14	AE5
AE19	AE24	AF4	AF16	AF18	AF20	-